

Errata
MSP430FE423 Microcontroller



ABSTRACT

This document describes the known exceptions to the functional specifications (advisories).

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1 Functional Advisories

Advisories that affect the device's operation, function, or parametrics.

✓ The check mark indicates that the issue is present in the specified revision.

Errata Number	Rev K	Rev I	Rev H	Rev G	Rev E
ESP1	✓	✓	✓	✓	✓
ESP2	✓	✓	✓	✓	✓
ESP3	✓	✓	✓	✓	✓
ESP4	✓	✓	✓	✓	✓
ESP5	✓	✓	✓	✓	✓
FLL3	✓	✓	✓	✓	✓
MPY2			✓		✓
SD1	✓	✓	✓	✓	✓
SD2	✓	✓	✓	✓	✓
TA12	✓	✓	✓	✓	✓
TA16	✓	✓	✓	✓	✓
TA21	✓	✓	✓	✓	✓
TAB22	✓	✓	✓	✓	✓
US15	✓	✓	✓	✓	✓
WDG2	✓	✓	✓	✓	✓

2 Preprogrammed Software Advisories

Advisories that affect factory-programmed software.

✓ The check mark indicates that the issue is present in the specified revision.

The device does not have any errata for this category.

3 Debug Only Advisories

Advisories that affect only debug operation.

✓ The check mark indicates that the issue is present in the specified revision.

Errata Number	Rev K	Rev I	Rev H	Rev G	Rev E
EEM20	✓	✓	✓	✓	✓

4 Fixed by Compiler Advisories

Advisories that are resolved by compiler workaround. Refer to each advisory for the IDE and compiler versions with a workaround.

✓ The check mark indicates that the issue is present in the specified revision.

Errata Number	Rev K	Rev I	Rev H	Rev G	Rev E
CPU4	✓	✓	✓	✓	✓

Refer to the following MSP430 compiler documentation for more details about the CPU bugs workarounds.

TI MSP430 Compiler Tools (Code Composer Studio IDE)

- [MSP430 Optimizing C/C++ Compiler](#): Check the --silicon_errata option
- [MSP430 Assembly Language Tools](#)

MSP430 GNU Compiler (MSP430-GCC)

- [MSP430 GCC Options](#): Check -msilicon-errata= and -msilicon-errata-warn= options
- [MSP430 GCC User's Guide](#)

IAR Embedded Workbench

- [IAR workarounds for msp430 hardware issues](#)

5 Nomenclature, Package Symbolization, and Revision Identification

The revision of the device can be identified by the revision letter on the [Package Markings](#) or by the [HW_ID](#) located inside the TLV structure of the device.

5.1 Device Nomenclature

To designate the stages in the product development cycle, TI assigns prefixes to the part numbers of all MSP MCU devices. Each MSP MCU commercial family member has one of two prefixes: MSP or XMS. These prefixes represent evolutionary stages of product development from engineering prototypes (XMS) through fully qualified production devices (MSP).

XMS – Experimental device that is not necessarily representative of the final device's electrical specifications

MSP – Fully qualified production device

Support tool naming prefixes:

X: Development-support product that has not yet completed Texas Instruments internal qualification testing.

null: Fully-qualified development-support product.

XMS devices and X development-support tools are shipped against the following disclaimer:

"Developmental product is intended for internal evaluation purposes."

MSP devices have been characterized fully, and the quality and reliability of the device have been demonstrated fully. TI's standard warranty applies.

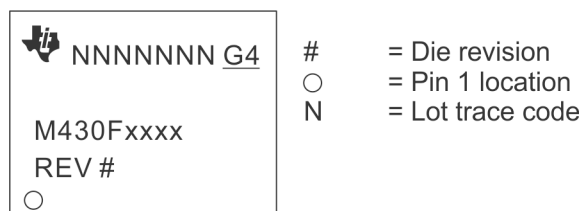
Predictions show that prototype devices (XMS) have a greater failure rate than the standard production devices. TI recommends that these devices not be used in any production system because their expected end-use failure rate still is undefined. Only qualified production devices are to be used.

TI device nomenclature also includes a suffix with the device family name. This suffix indicates the temperature range, package type, and distribution format.

5.2 Package Markings

PM64

LQFP (PM), 64 Pin



5.3 Memory-Mapped Hardware Revision (TLV Structure)

This device does not support reading the hardware revision from memory.

Further guidance on how to locate the TLV structure and read out the HW_ID can be found in the device User's Guide.

6 Advisory Descriptions

CPU4 *CPU Module*

Category Compiler-Fixed

Function PUSH #4, PUSH #8

Description The single operand instruction PUSH cannot use the internal constants (CG) 4 and 8. The other internal constants (0, 1, 2, -1) can be used. The number of clock cycles is different:

PUSH #CG uses address mode 00, requiring 3 cycles, 1 word instruction

PUSH #4/#8 uses address mode 11, requiring 5 cycles, 2 word instruction

Workaround Refer to the table below for compiler-specific fix implementation information.

IDE/Compiler	Version Number	Notes
IAR Embedded Workbench	IAR EW430 v2.x until v6.20	User is required to add the compiler flag option below. --hw_workaround=CPU4
IAR Embedded Workbench	IAR EW430 v6.20 or later	Workaround is automatically enabled
TI MSP430 Compiler Tools (Code Composer Studio)	v1.1 or later	
MSP430 GNU Compiler (MSP430-GCC)	MSP430-GCC 4.9 build 167 or later	

EEM20 *EEM Module*

Category Debug

Function Debugger might clear interrupt flags

Description During debugging read-sensitive interrupt flags might be cleared as soon as the debugger stops. This is valid in both single-stepping and free run modes.

Workaround None.

ESP1 *ESP Module*

Category Functional

Function Suspending the ESP430CE1

Description Suspending the ESP430 may create an invalid interrupt which can lead to a reset-like behavior of the module.

Workaround Set the bit 0x08 together with the ESPSUSP bit:
 bis.w #08h+ESPSUSP, &ESPCTL
 This bit also must be cleared when the suspend mode is exited.
 bic.w #08h+ESPSUSP, &ESPCTL
 NOTE:
 - After suspending the ESP430CE1 it can take up to 9 MCLK clock cycles before the CPU can access the SD16 registers.
 - An interrupt service routine for the SD16 is required.

```
// Shut down ESP (set Embedded Signal Processing into
// "Suspend" mode)
// ensure that it is not in measurement or calibration mode,
ESPCTL |= 0x08 + ESPSUSP;
// Set ESP into Suspend Mode
// incl. Bug Fix for Suspend Mode
// wait 9 clocks until proper access to the SD16 is possible
__delay_cycles(9);

MBCTL &= ~(IN0IFG + IN0IE);
// Clear any Pending MB interrupt and disable
// ESP interrupt
SD16CTL &= ~SD16REFON; // Switch Reference off
```

ESP2**ESP Module**

Category

Functional

Function

Negative Energy Flag Operation

Description

The NEGENFG negative energy flag treatment inside the ESP430 module is executed after each mains cycle and is set according to the energy accumulated during this period. Therefore the flag is set under two conditions:

- if during at least one mains cycle period over the last second the accumulated energy in the ACTENSPER register was negative
- if the accumulated energy in the ACTENERGY register is negative.

Workaround

If the indication of the negative energy status is required by the application, it can be done with the following sequence in CPU software.

1. Set negative energy bits: NE0 = 0, NE1 = 1 (negative energy is summed)
2. Perform the required steps manually software after new energy samples are available from the ESP430CE1:
 - Check if the energy is negative and set the negative energy flag
 - Correct the energy to positive values if required.

```
if ((msg_data & ENRDYFG))
{
if ((ACTENERGY1_HI & 0x8000) > 0 ) { // Negative Energy measured?
negenfg = 1; // set global neg. Energy Flag
}else{
negenfg = 0; // clear global neg. Energy Flag
}
}
```

```
if (negenfg == 1){ // Negative Energy measured?
total_energy -= (float)energy.l;
}else{
total_energy += (float)energy.l;
}
} // End of if ((msg_data & ENRDY)
```

ESP3**ESP Module**

Category	Functional
Function	Temperature measurement in Tamper mode could modify SD16 settings.
Description	<p>Unintended modification of the SD16 registers by the ESP can occur during temperature measurement when operating in Tamper mode. The following simultaneous events can trigger this:</p> <ol style="list-style-type: none"> 1. Meter is running in Tamper mode (Measuring on both I1 and I2 current channels) 2. Temperature measurement is requested 3. I2GT11FG in register ESP430_STAT0 changes state from logic "0" to "1" or logic "1" to "0" during the Temperature measurement.
Workaround	<p>Synchronize the request for Temperature measurement with the ENRDYFG or ENRDYME. Request for temperature measurement after the flag ENRDYFG=1, or when ENRDYME is set to 1. This ensures enough time for the temperature measurement before I2GT11FG changes state.</p>

ESP4 *ESP Module*

Category	Functional
Function	Suspending the ESP430 activity
Description	Due to timing violations between the ESP CPU and the MSP430 CPU, the SD16 converters are not switched off correctly if the ESP CPU is set into suspend mode immediately after the ESP CPU is checked for idle mode. This leads to an higher current consumption in low-power modes.
Workaround	Implement an additional wait loop of 16 clock cycles between checking the ESP for idle mode and set the ESP CPU into suspend mode.

```
while ((RET0 & 0x8000) != 0); // Wait for Idle mode
// wait 16 clocks to exclude timing violations between MSP430 CPU
// and ESP CPU
_NOP();_NOP();_NOP();_NOP();_NOP();_NOP();_NOP();_NOP();_NOP();--
_NOP();_NOP();_NOP();_NOP();_NOP();_NOP();_NOP();
// Shut down ESP (set Embedded Signal Processing into "Suspend" mode)
// ensure that it is not in measurement or calibration mode,
if ((RET0 & 0x8000) == 0)
{
ESPCTL |= 0x08 + ESPSUSP; // Set ESP into Suspend Mode
// incl. Bug Fix for Suspend Mode
}
```

ESP5 *ESP Module*

Category	Functional
Function	In two current mode, CAPIND detection works on current channel 1 only
Description	When using the ESP430 module in the two current mode, CAPIND detection works on current channel 1 only and does not work when using current channel 2. This could deliver wrong values if the current in channel 1 is near or equal 0.
Workaround	None

FLL3 *FLL Module***Category** Functional**Function** FLLDx = 11 for /8 may generate an unstable MCLK frequency**Description** When setting the FLL to higher frequencies using FLLDx = 11 (/8) the output frequency of the FLL may have a larger frequency variation (e.g. averaged over 2sec) as well as a lower average output frequency than expected when compared to the other FLLDx bit settings.**Workaround** None**MPY2** *MPY Module***Category** Functional**Function** Multiplier Result register corruption**Description** Depending on the address of the write instruction, writing to the multiplier result registers (RESHI, RESLO, or SUMEXT) may corrupt the result registers. The address dependency varies between a 2-word and a 3-word instructions.**Workaround** Ensure that a write instruction to an MPY result register (for example, mov.w #200, &RESHI) is not located at an address with the four least significant bits shown in Table 1:

Table 1. Sensitive Addresses for Write Access to MPY Result Registers MAB[3:0]

RESLOW 013Ah		RESHI 013Ch		SUMEXT 013Eh	
3 Word	2 Word	3 Word	2 Word	3 Word	2 Word
2	4	2	4	2	4
6	8	4	6	6	8
A	C	A	C	A	C
E	0	C	E	-	-

SD1 *SD Module***Category** Functional**Function** Reduced SINAD performance if SD16 clock source is greater than 6 MHz**Description** If the frequency of the SD16 input clock source is greater than 6 MHz, the performance of the SD16 may be degraded due to noise influencing the analog measurements under reduced SINAD.**Workaround** Writing 0x48 to memory location 0xBF configures the SD16 for optimized performance at input clock frequencies greater than 6 MHz.

Include the following code:

(unsigned char) 0xBF=0x48; // Write value 0x48 to memory address 0xBF

SD2 *SD Module***Category** Functional**Function** Internal short measurement influenced by external Ax.0 analog voltages**Description** Applying a common mode voltage other than VSS or a differential voltage to the analog inputs of the SD16 may influence the measurement accuracy when converting the internal

short channel (A7). The error under these conditions is proportional to the common-mode or differential voltage and is typically 150+ LSBs.

Workaround Avoid applying common-mode voltages other than VSS, or a differential input voltage during the measurement of the internal short channel.

TA12 *TA Module*

Category Functional

Function Interrupt is lost (slow ACLK)

Description Timer_A counter is running with slow clock (external TACLK or ACLK) compared to MCLK. The compare mode is selected for the capture/compare channel and the CCRx register is incremented by one with the occurring compare interrupt (if TAR = CCRx). Due to the fast MCLK the CCRx register increment (CCRx = CCRx+1) happens before the Timer_A counter has incremented again. Therefore the next compare interrupt should happen at once with the next Timer_A counter increment (if TAR = CCRx + 1). This interrupt gets lost.

Workaround Switch capture/compare mode to capture mode before the CCRx register increment. Switch back to compare mode afterwards.

TA16 *TA Module*

Category Functional

Function First increment of TAR erroneous when IDx > 00

Description The first increment of TAR after any timer clear event (POR/TACLR) happens immediately following the first positive edge of the selected clock source (INCLK, SMCLK, ACLK or TACLK). This is independent of the clock input divider settings (ID0, ID1). All following TAR increments are performed correctly with the selected IDx settings.

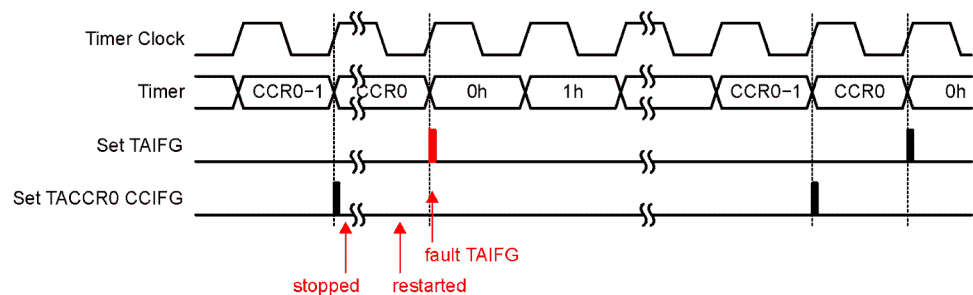
Workaround None

TA21 *TA Module*

Category Functional

Function TAIFG Flag is erroneously set after Timer A restarts in Up Mode

Description In Up Mode, the TAIFG flag should only be set when the timer counts from TACCR0 to zero. However, if the Timer A is stopped at TAR = TACCR0, then cleared (TAR=0) by setting the TACLR bit, and finally restarted in Up Mode, the next rising edge of the TACLK will erroneously set the TAIFG flag.



Workaround None.

TAB22	<i>TAB Module</i>
Category	Functional
Function	Timer_A/Timer_B register modification after Watchdog Timer PUC
Description	Unwanted modification of the Timer_A/Timer_B registers TACTL/TBCTL and TAIV/TBIV can occur when a PUC is generated by the Watchdog Timer(WDT) in Watchdog mode and any Timer_A/Timer_B counter register TACCRx/TBCCRx is incremented/decremented (Timer_A/Timer_B does not need to be running).
Workaround	<p>Initialize TACTL/TBCTL register after the reset occurs using a MOV instruction (BIS/BIC may not fully initialize the register). TAIV/TBIV is automatically cleared following this initialization.</p> <p>Example code:</p> <pre>MOV.W #VAL, &TACTL or MOV.W #VAL, &TBCTL</pre> <p>Where, VAL=0, if Timer is not used in application otherwise, user defined per desired function.</p>
US15	<i>USART Module</i>
Category	Functional
Function	UART receive with two stop bits
Description	USART hardware does not detect a missing second stop bit when SPB = 1. The Framing Error Flag (FE) will not be set under this condition and erroneous data reception may occur.
Workaround	None (Configure USART for a single stop bit, SPB = 0)
WDG2	<i>WDG Module</i>
Category	Functional
Function	Incorrectly accessing a flash control register
Description	If a key violation is caused by incorrectly accessing a flash control register, the watchdog interrupt flag is set in addition to the expected PUC.
Workaround	None

7 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from May 29, 2018 to May 19, 2021	Page
<ul style="list-style-type: none">Changed the document format and structure; updated the numbering format for tables, figures, and cross references throughout the document.....	5

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